2-530678-6 SUPERSEDED

AMP

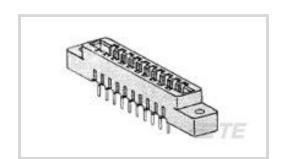
TE Internal #: 2-530678-6

TE Internal Description: CONN LOW PRO 22 POS 156X200C/L

View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > Standard Edge Connectors



Connector System: Board-to-Board

Number of Positions: 22

Centerline (Pitch): 3.96 mm [.156 in]

Termination Method to Wire & Cable: Solder Eyelet

Contact Mating Area Plating Material Thickness

PCB Contact Termination Area Plating Material Finish

Contact Mating Area Plating Material

Contact Underplating Material

Number of Dual Positions: 22

Features

Product Type Features

Product Type Features	
Connector System	Board-to-Board
Connector & Housing Type	Receptacle
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	22
Number of Dual Positions	22
Number of Rows	2
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Body Features	
Primary Product Color	Green
Contact Features	
Contact Retention Within Housing	With
PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]
Contact Type	Socket

.76 µm

Gold

Bright

Nickel



Contact Base Material Phosphor Browe Contact Current Rating (Max) 5 A Termination Features Termination Post & Tail Length 4.57 mml,18 in] Termination Method to PCB Through Hole - Solder Termination Method to PCB Solder Eyelet Mechanical Attachment Meting Retention Without Mating Alignment Without Contact Retention Iype Within Housing Locking Lance PCB Mount Alignment Without PCB Mount Retention With PCB Mount Retention With PCB Mount Retention With PCB Mount Retention Housing Board Mount Housing Features Concector Mounting Type Board Mount Housing Material Glass Filled Polyester Dimensions Card Slot Depth 7.49 mm[29 in] Connector Height 11.68 mm[46 in] Row-to-Row Spacing 5.08 mm[2 in] Usage Conditions Operating Temperature Range -55 – 105 °C[67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Guantity 90 Packaging Method Box	PCB Contact Termination Area Plating Material	Tin
Termination Features Termination Post & Tail Length 4.57 mm[.18 in] Termination Method to PCB 1 Through Hole - Solder Termination Method to Wire & Cable Solder Eyelet Mechanical Attachment Mating Retention Without Without Contact Retention Type Within Housing Locking Lance PCB Mount Alignment Without PCB Mount Retention Type Within Housing Housing Housing Locking Lance PCB Mount Retention Type Mounting Fars Connector Mounting Type Hounting Fars Connector Mounting Type Board Mount Housing Features Centraline (Pitch) 3.96 mm[.156 in] Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range 55 – 105 °C[.67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Features	Contact Base Material	Phosphor Bronze
Termination Post & Tail Length Termination Method to PCB Through Hole - Solder Termination Method to Wire & Cable Mechanical Attachment Mating Retention Mating Alignment Contact Retention Type Within Housing PCB Mount Alignment Without PCB Mount Retention With PCB Mount Retention Type Mounting Fars Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Jay6 mm[156 in] Class-Filled Polyester Dimensions Card Slot Depth Connector Hoight Tonnector Hoight Row to Row Spacing Departing Temperature Range Operating Temperature Range Packaging Features Packaging Features Packaging Features Packaging Features Packaging Guantity 90	Contact Current Rating (Max)	5 A
Termination Method to PCB Termination Method to Wire & Cable Solder Eyelet Mechanical Attachment Mating Retention Without Mating Alignment Without Contact Retention Type Within Housing PCB Mount Alignment With PCB Mount Retention Type Mounting Fars Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material Connector Height T.49 mm[.29 in] Connector Height Row-to-Row Spacing Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Packaging Guantity 90	Termination Features	
Termination Method to Wire & Cable Mechanical Attachment Mating Retention Mating Alignment Without Contact Retention Type Within Housing PCB Mount Alignment Without PCB Mount Retention PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Jay6 mml. 156 in Housing Material Class-Filled Polyester Dimensions Card Slot Depth 7.49 mml. 29 in Connector Height 11.68 mml. 46 in] Row to Row Spacing Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Guantity 90	Termination Post & Tail Length	4.57 mm[.18 in]
Mechanical Attachment Without Mating Alignment Without Contact Retention Type Within Housing Locking Lance PCB Mount Alignment Without PCB Mount Retention With PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 3.96 mm(.156 in) Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm(.29 in) Connector Height 11.68 mm(.20 in) Row-to-Row Spacing 5.08 mm(.20 in) Usage Conditions Operating Temperature Range -55 - 105 °C[-67 - 221 °F] Operation/Application Power Packaging Features Packaging Guantity 90	Termination Method to PCB	Through Hole - Solder
Mating Retention Without Mating Alignment Without Contact Retention Type Within Housing Locking Lance PCB Mount Alignment Without PCB Mount Retention PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 3.96 mm[.156 in] Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operation/Application Circuit Application Power Packaging Features Packaging Features Packaging Quantity 90	Termination Method to Wire & Cable	Solder Eyelet
Mating Alignment Contact Retention Type Within Housing PCB Mount Alignment PCB Mount Retention PCB Mount Retention PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 11 Jousing Material Card Slot Depth Connector Height Row to Row Spacing Usage Conditions Operating Temperature Range Circuit Application Power Packaging Features Packaging Guantity PCB Mount Retention Type Within Housing Without With Without Without With Without With Without With Without With Without With Without With With With With Without With Would With With With Would With With With With With With With With Would With With With With With Mounting Ears Mounting Ears Would With With With With With Mounting Ears Would With With With With With With With Mounting Ears Would With With With Would With With With Would With With With With With Would With With With	Mechanical Attachment	
Contact Retention Type Within Housing PCB Mount Alignment Without PCB Mount Retention PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 3.96 mm[.156 in] Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height Row-to-Row Spacing Usage Conditions Operating Temperature Range Operation/Application Circuit Application Power Packaging Features Packaging Quantity Polyester Packaging Quantity Polyester Power	Mating Retention	Without
PCB Mount Alignment Without PCB Mount Retention With PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 3.96 mm[.156 in] Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range -55 = 105 °C[-67 - 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Mating Alignment	Without
PCB Mount Retention Type Mounting Ears Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 3.96 mm[.156 in] Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Contact Retention Type Within Housing	Locking Lance
PCB Mount Retention Type Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material Card Slot Depth Connector Height Connector Height Row-to-Row Spacing Usage Conditions Operating Temperature Range Circuit Application Packaging Features Packaging Quantity Mounting Ears Mounting Ears Board Mount Board Mount Abount Board Mount Abount All All Mounting Ears Board Mount Board Mount Abount Board Mount All All Mounting Ears Board Mount All All Mounting Ears Board Mount Board Mount Board Mount Board Mount Board Mounting Board Mount Board Mounting Board Moun	PCB Mount Alignment	Without
Connector Mounting Type Housing Features Centerline (Pitch) Housing Material Dimensions Card Slot Depth Connector Height Row-to-Row Spacing Usage Conditions Operating Temperature Range Circuit Application Circuit Application Packaging Features Packaging Quantity Base Seat Mount Board Mount Seat House Board Mount Board Mount Board Mount Seat House Board Mount	PCB Mount Retention	With
Housing Features Centerline (Pitch) Housing Material Class-Filled Polyester Dimensions Card Slot Depth Connector Height Row-to-Row Spacing Usage Conditions Operating Temperature Range Circuit Application Circuit Application Power Packaging Features Packaging Quantity 90	PCB Mount Retention Type	Mounting Ears
Centerline (Pitch) Housing Material Card Slot Depth Connector Height Row-to-Row Spacing Usage Conditions Operating Temperature Range Circuit Application Circuit Application Packaging Features Packaging Quantity 3.96 mm[.156 in] Glass-Filled Polyester 7.49 mm[.29 in] 11.68 mm[.46 in] 5.08 mm[.2 in] 5.08 mm[.2 in] Power	Connector Mounting Type	Board Mount
Housing Material Glass-Filled Polyester Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Housing Features	
Dimensions Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Centerline (Pitch)	3.96 mm[.156 in]
Card Slot Depth 7.49 mm[.29 in] Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Housing Material	Glass-Filled Polyester
Connector Height 11.68 mm[.46 in] Row-to-Row Spacing 5.08 mm[.2 in] Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Dimensions	
Row-to-Row Spacing Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Card Slot Depth	7.49 mm[.29 in]
Usage Conditions Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Connector Height	11.68 mm[.46 in]
Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application Circuit Application Power Packaging Features Packaging Quantity 90	Row-to-Row Spacing	5.08 mm[.2 in]
Operation/Application Circuit Application Packaging Features Packaging Quantity 90	Usage Conditions	
Circuit Application Power Packaging Features Packaging Quantity 90	Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Packaging Features Packaging Quantity 90	Operation/Application	
Packaging Quantity 90	Circuit Application	Power
	Packaging Features	
Packaging Method Box	Packaging Quantity	90
	Packaging Method	Box

Product Compliance

For compliance documentation, visit the product page on TE.com>



EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2023 (235) SVHC > Threshold: Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought





















Documents

Product Drawings

CONN LOW PRO 22 POS 156X200C/L

English

Product Specifications

Product Specification

English

Instruction Sheets

Instruction Sheet (U.S.)

English

REPLACING CONTACTS IN AMP LOW PROFILE EDGE CONNECTORS

English

09/18/2024 12:01PM | Page 4